

AMENDMENTS TO CLAIMS

1. (Currently Amended) A board for printed wiring comprising:

a substrate;

an adhesive layer of a metal oxide provided on a surface of the substrate; and

an electromagnetic wave absorbing laminate provided on the adhesive layer, and said
electromagnetic wave absorbing laminate comprising:

(a) a magnetic layer with a thickness of not greater than 250nm comprising a plurality of
magnetic particles having an average particle diameter of 1 to 150 nm and isolated from each other
by an electrically insulative material; and

(b) an electrically insulative layer with a thickness of 1 to 50nm;

the magnetic layer and the electrically insulative layer being alternately stacked in a multi-
layer structure having at least two layers of the magnetic layer.
2. (Original) A board for printed wiring as set forth in claim 1, wherein the magnetic
particles are composed of at least one metal selected from the group consisting of Fe, Co and Ni or
the oxide of said metal.
3. (Original) A board for printed wiring as set forth in claim 1, wherein the magnetic
particles are respectively coated with electrically insulative films to provide a plurality of composite
particles, and said composite particles are bound each other to constitute the magnetic layer.

4. (Original) A board for printed wiring as set forth in claim 3, wherein the electrically insulative films are composed of the oxide of at least one metal selected from the group consisting of Si, Al, Ti and Zr, an amine derivative, an alkanethiol derivative or a resin.

5. (Original) A board for printed wiring as set forth in claim 3, wherein the electrically insulative films have a covering ratio of 10 to 50 vol% based on the total amount of the composite particles.

6. (Original) A board for printed wiring as set forth in claim 3, wherein the plurality of composite particles are bound by a binder to constitute the magnetic layer.

7. (Original) A board for printed wiring as set forth in claim 1, wherein the adhesive layer is composed of at least a Ti containing metal oxide.

8. (Original) A board for printed wiring as set forth in claim 1, wherein the adhesive layer has a thickness of 3 to 150 nm.

9. (Original) A board for printed wiring as set forth in claim 1, wherein the electrically insulative layer is composed of the oxide of at least one metal selected from the group consisting of Si, Al, Ti and Zr, or a curable resin.

10. (Original) A board for printed wiring as set forth in claim 1, wherein the electromagnetic wave absorbing laminate has a complex permeability μ having a real part μ' and an

Application No.: 10/669,018

imaginary part μ'' which satisfy a relationship $\mu' > \mu''$ in a predetermined frequency range within a high frequency band up to 2GHz.